Dual Matched 40 V, 6.0 A, Low V_{CE(sat)} NPN Transistor

These transistors are part of the ON Semiconductor e^2 PowerEdge family of Low $V_{CE(sat)}$ transistors. They are assembled to create a pair of devices highly matched in all parameters, including ultra low saturation voltage $V_{CE(sat)}$, high current gain and Base/Emitter turn on voltage.

Typical applications are current mirrors, differential amplifiers, DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- Current Gain Matching to 10%
- Base Emitter Voltage Matched to 2 mV
- This is a Pb-Free Device

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V_{CEO}	40	Vdc
Collector-Base Voltage	V_{CBO}	40	Vdc
Emitter-Base Voltage	V_{EBO}	6.0	Vdc
Collector Current - Continuous	I _C	3.0	Α
Collector Current - Peak	I _{CM}	6.0	Α
Electrostatic Discharge	ESD	HBM Class 3B MM Class C	

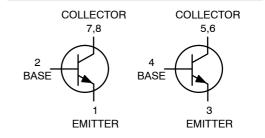
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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$\begin{array}{c} \text{40 VOLTS} \\ \text{6.0 AMPS} \\ \text{NPN LOW V}_{\text{CE(sat)}} \text{ TRANSISTOR} \\ \text{EQUIVALENT R}_{\text{DS(on)}} \text{ 44 m} \Omega \end{array}$





SOIC-8 CASE 751 STYLE 16

DEVICE MARKING



N40301 = Specific Device Code A = Assembly Location

Y = Year WW = Work Week • Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS40301MDR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
SINGLE HEATED			
Total Device Dissipation (Note 1) T _A = 25°C	P _D	576	mW
Derate above 25°C		4.6	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ heta JA}$	217	°C/W
Total Device Dissipation (Note 2) T _A = 25°C	P _D	676	mW
Derate above 25°C		5.4	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	185	°C/W
DUAL HEATED (Note 3)			
Total Device Dissipation (Note 1) $T_{\Delta} = 25^{\circ}C$	P _D	653	mW
Derate above 25°C		5.2	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ heta JA}$	191	°C/W
Total Device Dissipation (Note 2) $T_A = 25^{\circ}C$	P _D	783	mW
Derate above 25°C		6.3	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	160	°C/W
Junction and Storage Temperature Range	T _J , T _{stq}	-55 to +150	°C

FR-4 @ 10 mm², 1 oz. copper traces, still air.
 FR-4 @ 100 mm², 1 oz. copper traces, still air.
 Dual heated values assume total power is the sum of two equally powered devices.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	1				1
Collector – Emitter Breakdown Voltage $(I_C = 10 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	40	-	_	Vdc
Collector – Base Breakdown Voltage $(I_C = 0.1 \text{ mAdc}, I_E = 0)$	V _(BR) CBO	40	-	-	Vdc
Emitter – Base Breakdown Voltage (I _E = 0.1 mAdc, I _C = 0)	V _{(BR)EBO}	6.0	-	-	Vdc
Collector Cutoff Current (V _{CB} = 40 Vdc, I _E = 0)	I _{CBO}	-	-	0.1	μAdc
Emitter Cutoff Current (V _{EB} = 6.0 Vdc)	I _{EBO}	-	-	0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 4) $ \begin{aligned} &(I_C = 10 \text{ mA, V}_{CE} = 2.0 \text{ V}) \\ &(I_C = 500 \text{ mA, V}_{CE} = 2.0 \text{ V}) \\ &(I_C = 1.0 \text{ A, V}_{CE} = 2.0 \text{ V}) \\ &(I_C = 2.0 \text{ A, V}_{CE} = 2.0 \text{ V}) \\ &(I_C = 2.0 \text{ A, V}_{CE} = 2.0 \text{ V}) \end{aligned} $	h _{FE}	200 200 180 180 0.9	400 350 340 320 0.99	- - - -	
Collector – Emitter Saturation Voltage (Note 4) $ \begin{pmatrix} I_C = 0.1 \text{ A, } I_B = 0.010 \text{ A} \end{pmatrix} $ $ \begin{pmatrix} I_C = 1.0 \text{ A, } I_B = 0.100 \text{ A} \end{pmatrix} $ $ \begin{pmatrix} I_C = 1.0 \text{ A, } I_B = 0.010 \text{ A} \end{pmatrix} $ $ \begin{pmatrix} I_C = 2.0 \text{ A, } I_B = 0.200 \text{ A} \end{pmatrix} $	V _{CE(sat)}	- - - -	0.008 0.044 0.080 0.082	0.011 0.060 0.115 0.115	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = 1.0 \text{ A}, I_B = 0.01 \text{ A})$	V _{BE(sat)}	_	0.780	0.900	V
Base – Emitter Turn–on Voltage (Note 4) (I _C = 0.1 A, V _{CE} = 2.0 V) (I _C = 0.1 A, V _{CE} = 2.0 V) (Note 6)	$V_{BE(on)}$ $V_{BE(1)} - V_{BE(2)}$	- -	0.650 0.3	0.750 2.0	V mV
Cutoff Frequency ($I_C = 100 \text{ mA}$, $V_{CE} = 5.0 \text{ V}$, $f = 100 \text{ MHz}$)	f _T	100	-	-	MHz
Input Capacitance (V _{EB} = 0.5 V, f = 1.0 MHz)	Cibo	-	320	450	pF
Output Capacitance (V _{CB} = 3.0 V, f = 1.0 MHz)	Cobo	-	40	50	pF
SWITCHING CHARACTERISTICS					
Delay ($V_{CC} = 30 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _d	-	-	100	ns
Rise ($V_{CC} = 30 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _r	-	-	100	ns
Storage (V _{CC} = 30 V, I _C = 750 mA, I _{B1} = 15 mA)	t _s	-	-	780	ns
Fall (V _{CC} = 30 V, I _C = 750 mA, I _{B1} = 15 mA)	t _f	-	-	110	ns

Pulsed Condition: Pulse Width = 300 μsec, Duty Cycle ≤ 2%.
 h_{FE(1)}/h_{FE(2)} is the ratio of one transistor compared to the other transistor within the same package. The smaller h_{FE} is used as numerator.
 V_{BE(1)} - V_{BE(2)} is the absolute difference of one transistor compared to the other transistor within the same package.

TYPICAL CHARACTERISTICS

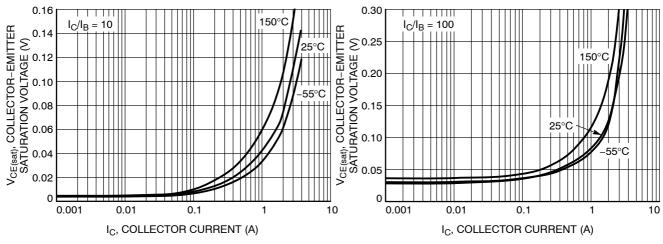


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

Figure 2. Collector Emitter Saturation Voltage vs. Collector Current

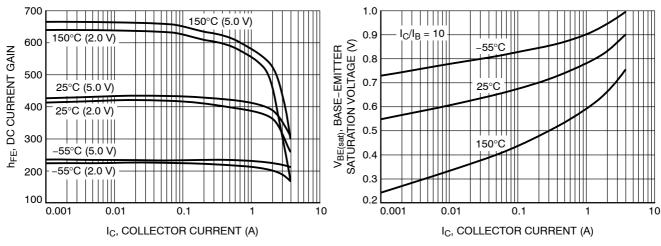


Figure 3. DC Current Gain vs. Collector Current

Figure 4. Base Emitter Saturation Voltage vs.
Collector Current

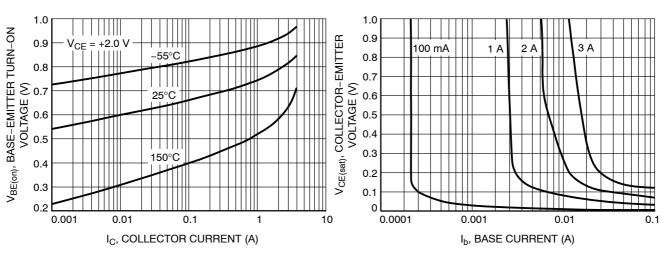


Figure 5. Base Emitter Turn-On Voltage vs.
Collector Current

Figure 6. Saturation Region

TYPICAL CHARACTERISTICS

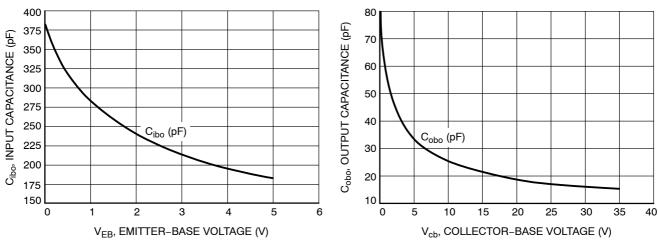


Figure 7. Input Capacitance

Figure 8. Output Capacitance

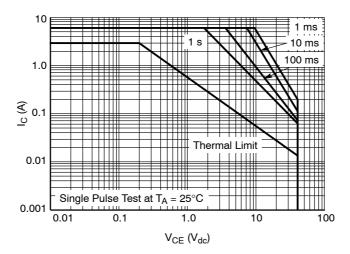
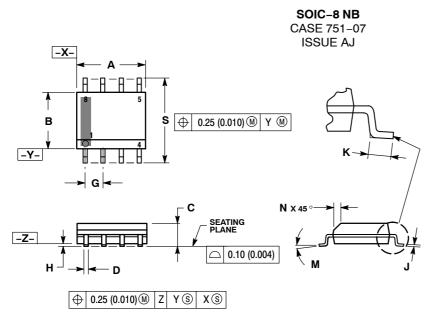
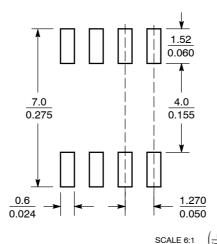


Figure 9. Safe Operating Area

PACKAGE DIMENSIONS



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.053	0.069		
D	0.33	0.51	0.013	0.020		
G	1.27	1.27 BSC		0.050 BSC		
Н	0.10	0.25	0.004	0.010		
J	0.19	0.25	0.007	0.010		
K	0.40	1.27	0.016	0.050		
М	0 °	8 °	0 °	8 °		
N	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228	0 244		

STYLE 16:

- PIN 1. EMITTER, DIE #1
 - BASE, DIE #1
 - 3. EMITTER, DIE #2 BASE, DIE #2 4.

 - COLLECTOR, DIE #2 COLLECTOR, DIE #2
 - COLLECTOR, DIE #1
 - COLLECTOR, DIE #1

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